SLOVENSKI STANDARD
SIST EN IEC 60749-39:2022

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Nadomešča:
SIST EN 60749-39:2007

Polprevodniški elementi - Mehanske in klimatske preskusne metode - 39. del: Meritve prepuščanja vlage organskih materialov in njihove vodotopnosti za polprevodniške komponente (IEC 60749-39:2021)

Semiconductor devices - Mechanical and climatic test methods - Part 39: Measurement of moisture diffusivity and water solubility in organic materials used for semiconductor components (IEC 60749-39:2021)

Halbleiterbauelemente - Mechanische und klimatische Prüfverfahren - Teil 39: Messung des Feuchtediffusionskoeffizienten und der Wasserlöslichkeit in organischen Werkstoffen, welche bei Halbleiter-Komponenten verwendet werden (IEC 60749-39:2021)

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 39: Mesure de la diffusion d'humidité et de l'hydrosolubilité dans les matériaux organiques utilisés dans les composants à semiconducteurs (IEC 60749-39:2021)

Ta slovenski standard je istoveten z: **EN IEC 60749-39:2022**

ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

SIST EN IEC 60749-39:2022 **en**

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 60749-39

January 2022

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Supersedes EN 60749-39:2006 and all of its amendments and corrigenda (if any)

English Version

Semiconductor devices - Mechanical and climatic test methods - Part 39: Measurement of moisture diffusivity and water solubility in organic materials used for semiconductor components (IEC 60749-39:2021)

Dispositifs à semiconducteurs - Méthodes d'essais mécaniques et climatiques - Partie 39: Mesure de la diffusivité d'humidité et de l'hydrosolubilité dans les matériaux organiques utilisés dans les composants à semiconducteurs (IEC 60749-39:2021)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 47/2652/CDV, future edition 2 of IEC 60749-39, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 60749-39:2022.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2022-10-03
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2025-01-03

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Endorsement notice

The text of the International Standard IEC 60749-39:2021 was approved by CENELEC as a European Standard without any modification.

Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

Publication	Year	Title	EN/HD	Year
IEC 60749-20	-	Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	EN IEC 60749-20	-

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SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 39: Measurement of moisture diffusivity and water solubility in organic materials used for semiconductor components

FOREWORD

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This second edition, based on JEDEC document JESD22-A120B, cancels and replaces the first edition published in 2006. It is used with permission of the copyright holder, JEDEC Solid State Technology Association. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) updated procedure for "dry weight" determination.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/2652/CDV	47/2725/RVC

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all the parts of the IEC 60749 series, under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.